

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. – 14. (cancelled)

15. (previously presented) A method of manufacturing a circuit board comprising:

the step of mounting a first component on a substrate by solder connection;

the step of arranging an anisotropic conductive film on a predetermined position of the substrate;

the step of arranging a second component on the anisotropic conductive film; and

the step of thermocompression-bonding the second component to said substrate with said anisotropic conductive film held therebetween;

wherein said step of arranging said anisotropic conductive film on the predetermined position of said substrate is performed after said step of mounting the first component on said substrate by the solder connection.

16. (previously presented) A method of manufacturing a circuit board according to claim 15, wherein said step of mounting said first component on said substrate by the solder connection includes a reflow treatment.

17. – 20. (cancelled)

21. (previously presented) A method of manufacturing a circuit board in which components are mounted thereto, comprising:

- a.) selecting a band region on a surface of the circuit board;
- b.) soldering a first component onto the circuit board outside of the band region; and
- c.) after step b.), mounting a second component on the substrate within the band region with an anisotropic conductive film.

22. (currently amended) The method of claim 21 where step c.) is performed with a heated compression bonding head, and

wherein the band region is selected to correspond generally to the areas over which the head travels during step c.) thereby preventing impact of the head with the first ~~components~~component and isolating the first ~~components~~component from the heat generated by the head.

23. (currently amended) The method of claim ~~22~~15 wherein the first ~~components~~arecomponent is selected from the group of passive and mechanical components, and the second component ~~is~~comprises a semiconductor device.

24. (currently amended) The method of claim ~~22~~15 wherein:

_____ the second component is mounted within a band region selected on a surface of the substrate;

_____ the step of thermocompression-bonding is performed with a compression bonding head; and

_____ the band region is wider than the head.

25. (currently amended) The method of claim 22-24 wherein alignment marks are provided outside the band region.

26. (currently amended) The method of claim 24-24 wherein the bonding region is selected ~~step a.) is performed by~~ performing a solder reflow process.

27. (currently amended) The method of claim 24-24 wherein the band region divides a first set of first components on one part of the substrate and a second set of first components on a second part of the substrate.

28. (currently amended) The method of claim 23 wherein the second ~~components are~~ component is selected from the group of a power source IC and a power source LSI.

29. (currently amended) The method of claim 24-24 wherein the band region extends from one end of the substrate to another end of the substrate.

30. (currently amended) The method of claim ~~21~~24 wherein the band region extends rectilinearly along the substrate.

31. (currently amended) The method of claim ~~21~~24 ~~which~~ further ~~comprising~~comprises:

forming wiring patterns on the substrate in the band region.

32. (currently amended) The method of claim ~~21~~15 ~~which~~ further ~~comprising~~comprises:

forming a dummy electrode at a position associated with a ~~the~~ second component.